

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

1. (currently amended) An LCD driver IC chip comprising:
a plurality of transistors in an internal semiconductor device circuit;
a pad member connected to [[an]] the internal semiconductor device circuit and having an electrical connection region to [[the]] an exterior;
at least one insulating film formed at a peripheral portion of the pad member and around the electrical connection region;
a metal layer covering the pad member and the insulating film; and
a bump electrode provided on the metal layer, wherein the bump electrode and the pad member lie above ~~at least a part of the semiconductor device circuit the~~ plurality of transistors with an insulating interlayer provided therebetween.

2. (currently amended) An integrated circuit chip comprising:
a plurality of device circuit circuits;
a transistor plurality of transistors in each of said device circuit circuits;
a pad positioned above said ~~transistor~~ plurality of transistors and connected to each of said device circuit circuits;
an insulating interlayer between said pad and said plurality of transistors transistor; and
a bump electrode on said pad and above said plurality of transistors.

3. (currently amended) The chip of claim 2 wherein each of the device circuit circuits further comprises are one of an input circuit and an output circuit.
4. (original) The chip of claim 2 wherein the pad further comprises one of an input pad and an output pad.
5. (cancelled)
6. (currently amended) The chip of claim 2 further comprising a via interconnecting said pad and each of said device circuit circuits.
7. (original) The chip of claim 6 further comprising a lead layer of said insulating interlayer interconnecting said via and said pad.
8. (original) The chip of claim 2 further comprising a passivation film formed at a peripheral portion of the pad.
9. (original) The chip of claim 8 further comprising a metal layer covering said passivation film and said pad.
10. (original) The chip of claim 9 wherein said metal layer is interposed between said pad and said bump.